

SyChip SN3021 IEEE802.15.4/ZigBee Smart Energy Module

User Manual and Datasheet

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1 System Descriptions

1.1 Applications

SyChip's SN3021 module is a standard-based wireless transceiver targeting the Smart Energy market with low power consumption, high transmit power (20 dBm typ.) and high receiver sensitivity (-103 dBm). It is based upon the IEEE 802.15.4 wireless network specification. The module can be used to develop applications supporting the ZigBee PRO Smart Energy application profile. The SN3021 module operates in the 2.4 GHz unlicensed ISM frequency band for worldwide deployment.

1.2 Module Summary

- Dimensions: $27.20 \times 14.75 \times 2.90$ mm³
- Ember EM357 high-performance, integrated ZigBee/802.15.4 chipset
- Supply voltage: 2.4V to 3.4V
- Data logging memory: 8 Mbits serial flash
- Security: 128-bit AES
- External antenna launch pad
- Host Interface: SPI, UART
- Meter interface: I2C, GPIO
- ADC ports: 6 x 14-bit
- RoHS compliant
- MSL JEDEC level 3

1.3 Block Diagram

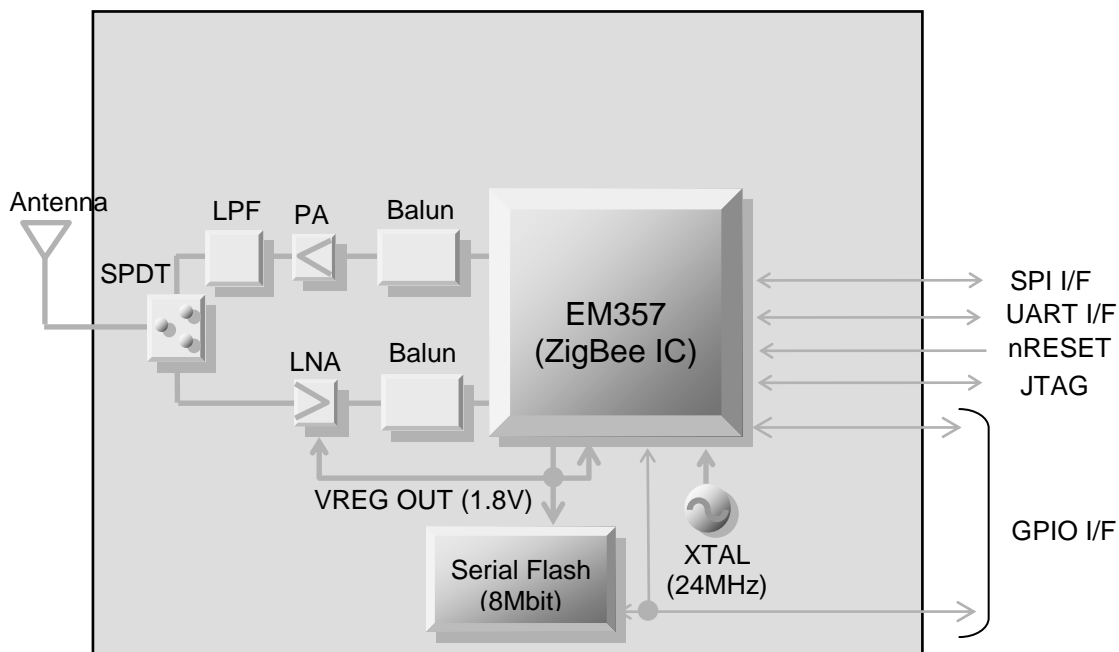


Figure 1 SN3021 Module Block Diagram

1.4 Acronyms

- ADC Analog to Digital Converter
- AMR Automatic Meter Reading
- GPIO General-Purpose Input-Output
- I2C Intelligent Interface Controller
- ISM Industrial, Scientific and Medical
- MAC Medium Access Control
- MSL Moisture Sensitivity Level
- PER Packet Error Rate
- ROHS Restriction of Hazardous Substances
- SPI Serial Peripheral Interface
- UART Universal Asynchronous Receiver-Transmitter
- WPAN Wireless Personal Area Network

2 Mechanical Specifications

2.1 Module Dimension

Parameter	Typical	Units
Dimension (LxWxH)	27.20 x 14.75 x 2.90	mm
Dimension tolerances (LxWxH)	± 0.20 x ± 0.20 x ± 0.15	mm

2.2 Module top and side view

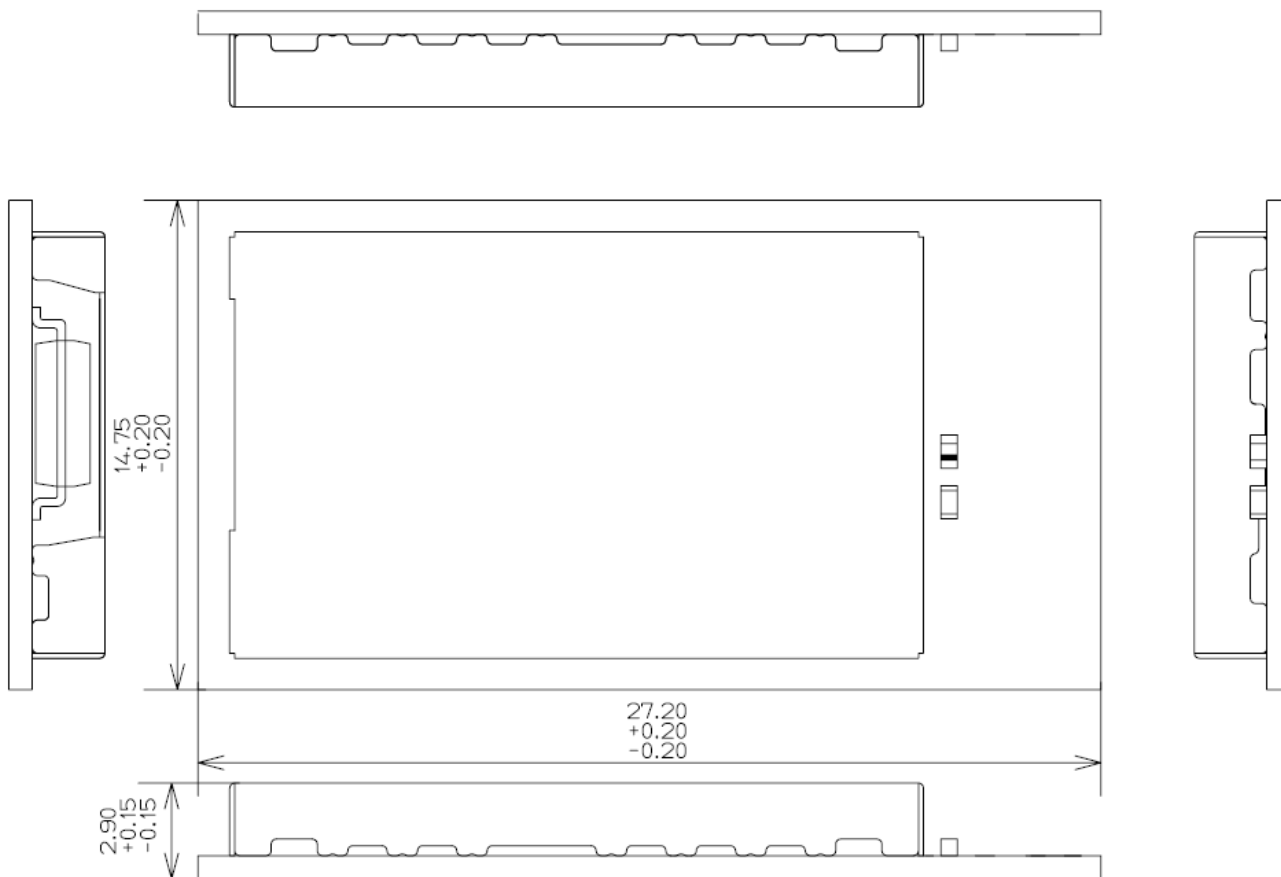


Figure 2 Module Top and Side View

2.3 Module bottom view

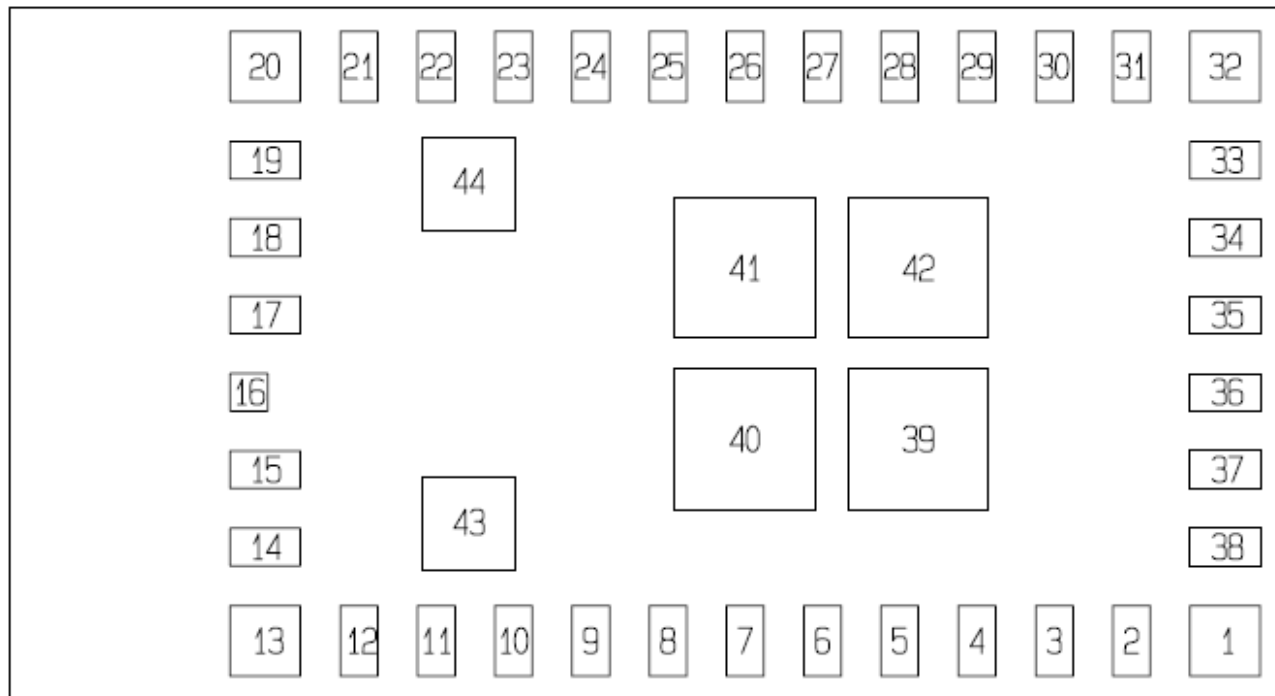


Figure 3 Module Bottom View

2.4 Detailed mechanical data (top view)

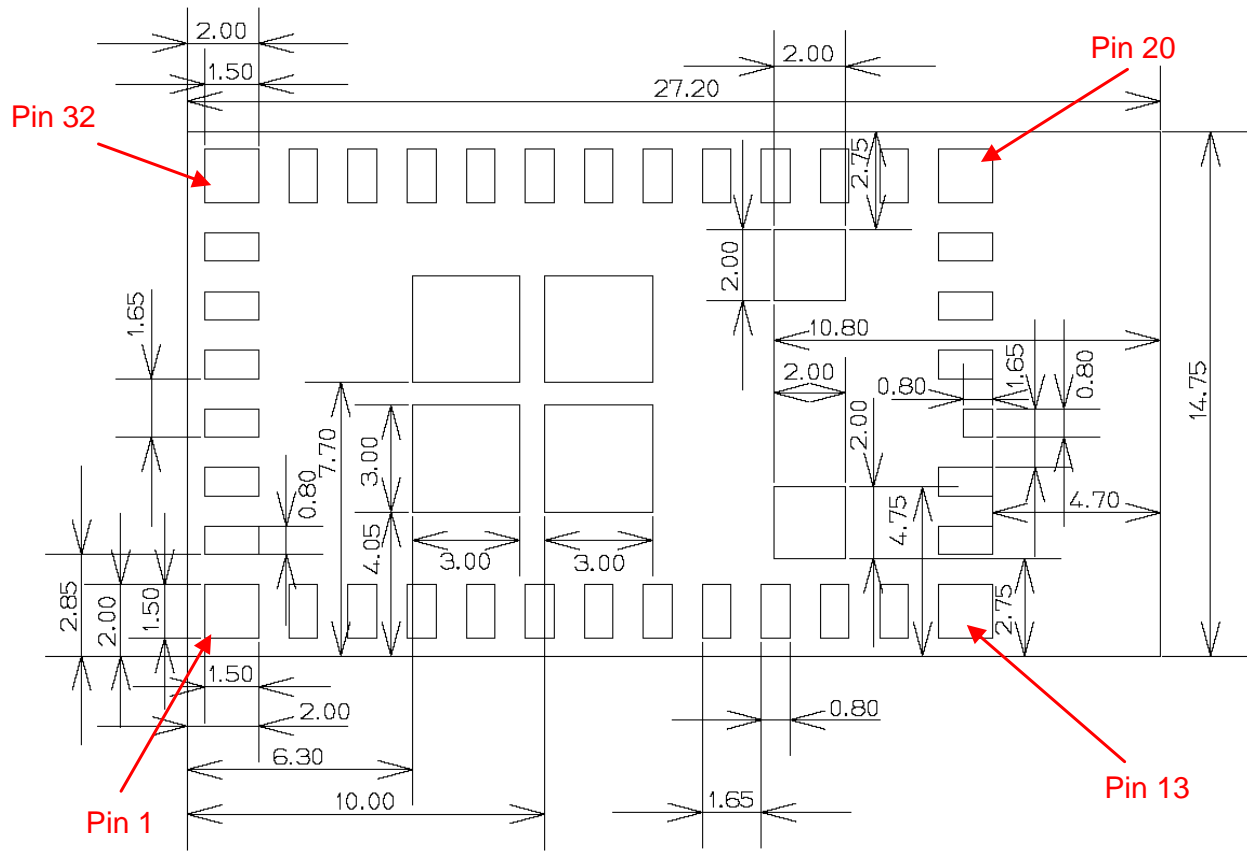


Figure 4 Detailed Mechanical Data (top view)

2.5 Module Pin-out

Table 1 Module Connector Signal Description

Pin #	Pin name	I/O	Description
1	GND	-	Ground
2	Reserved	O	Internal serial flash on/off control (active low), for debugging use only
3	PC4/JTMS	I/O	Programmable I/O control available to the host, or JTAG mode select
4	PB0/IRQA	I/O	Programmable I/O control available to the host, or an interrupt input
5	Reserved	O	Internal serial flash nCS, for debugging use only
6	PB6/ADC1/IRQB	I/O	Programmable I/O control available to the host, or ADC input, or an interrupt input
7	PC1/ADC3	I/O	Programmable I/O control available to the host, or an ADC input
8	SWCLK/JTCK	I	JTAG/Serial Wire debugging port clock
9	PC0/JRST/IRQD	I/O	Programmable I/O control available to the host, or an interrupt input, or the JTAG reset input
10	GND	-	Ground
11	PB5/ADC0	I/O	Programmable I/O control available to the host, or an ADC input
12	GND	-	Ground
13	GND	-	Ground
14	GND	-	Ground
15	GND	-	Ground

Pin #	Pin name	I/O	Description
16	Antenna	I/O	External antenna feed
17	GND	-	Ground
18	Reserved	O	Used internally as the LNA on (active low), for debugging use only
19	nRESET	I	Module reset signal (Internal pull-up)
20	GND	-	Ground
21	GND	-	Ground
22	PA3	I/O	Programmable I/O control available to the host,
23	GND	-	Ground
24	PC6/OSC32B	I/O	Programmable I/O control available to the host, or 32.768kHz crystal
25	PC7/OSC32A	I/O	Programmable I/O control available to the host, or 32.768kHz crystal
26	SC1SCLK/PB3	I/O	SPI port 1 clock , or programmable I/O control available to the host,
27	Reserved	O	Used internally as the serial flash MOSI, for debugging use only
28	Reserved	O	Used internally as the serial flash MISO, for debugging use only
29	VBATT	PI	Module power supply
30	Reserved	O	Used internally as the serial flash clock, for debugging use only
31	PA4/ADC4	I/O	Programmable I/O control available to the host, or ADC input
32	GND	-	Ground
33	PA5/ADC5/nBOOTMODE	I/O	Programmable I/O control available to the host, or ADC input, or Boot control, must be left open or pulled high during the reset to enable the normal firmware boot process.

Pin #	Pin name	I/O	Description
34	SC1MISO(s)/ SC1MOSI(m)/TXD/PB1/SC1SDA	I/O	SPI port 1 MISO (slave)/ MOSI (master) signal, UART TXD signal, I2C port 1 DATA signal, or programmable I/O control available to the host.
35	SC1MOSI(s)/ SC1MISO(m)/RXD/PB2/SC1SCL	I/O	SPI port 1 MOSI (slave)/ MISO (master) signal, UART RXD signal, I2C port 1 CLK signal, or programmable I/O control available to the host.
36	PC2/JTDO/SWO	I/O	Programmable I/O control available to the host, or Serial Wire port OUTPUT signal, or JTAG data out
37	SC1nSSEL/PB4	I/O	SPI port 1 slave select, or programmable I/O control available to the host,
38	PC3/JTDI	I/O	Programmable I/O control available to the host, or JTAG data in
39	GND	-	Ground
40	GND	-	Ground
41	GND	-	Ground
42	GND	-	Ground
43	GND	-	Ground
44	GND	-	Ground

3 DC Electrical Specifications

3.1 Typical Power Consumption

Table 2 Typical Power Consumption

Item	Condition	Values			Units
		Min	Typ	Max	
Sleep mode	VCC = 3.0V, TAMB = 25°C Internal RC oscillator on Processor, radio, peripherals off		1.2		μA
Standby mode	VCC = 3.0V, TAMB = 25°C Processor on Radio and peripherals off		10		mA
Receive mode	VCC = 3.0V, TAMB = 25°C Radio receive chain on		35		mA
Transmit mode (+20dBm)	VCC = 3.0V, TAMB = 25°C Radio transmit chain on		160		mA
Serial controller current	For each controller at maximum data rate		0.2		mA
General purpose timer current	For each timer at maximum clock rate		0.25		mA
General purpose ADC current	At maximum sample rate, DMA enabled		1.1		mA

3.2 Digital IO Specification

VCC = 3.0V, TAMB = 25°C, NORMAL MODE¹ unless otherwise stated

Table 3 Digital IO Specification

Item	Condition	Symbol	Values			Units
			Min	Typ	Max	
Input current for logic 0		I_{IL}			-0.5	μA
Input current for logic 1		I_{IH}			0.5	μA
Low Schmitt switching threshold	Schmitt input threshold going from high to low	V_{SWIL}	$0.42 \times V_{CC}$		$0.5 \times V_{CC}$	V

¹ NORMAL MODE as defined by Ember for EM357.

High Schmitt switching threshold	Schmitt input threshold going from low to high	V_{SWIH}	$0.62 \times V_{CC}$		$0.8 \times V_{CC}$	V
Output voltage for logic 0	$I_{OL} = 4\text{mA}$ (8mA) for standard (high current) pads	V_{OL}	0		$0.18 \times V_{CC}$	V
Output voltage for logic 1	$I_{OH} = 4\text{mA}$ (8mA) for standard (high current) pads	V_{OH}	$0.82 \times V_{CC}$		V_{CC}	V
Output Source Current	Standard current pad	I_{OHS}			4	mA
Output Sink current	Standard current pad	I_{OLS}			4	mA
Output Source Current	High current pad	I_{OHH}			8	mA
Output Sink current	High current pad	I_{OLH}			8	mA
Total output current		$I_{OH} + I_{OL}$			40	mA

4 RF Specifications

$V_{CC} = 3.0\text{V}$, $T_{AMB} = 25^{\circ}\text{C}$, NORMAL MODE measured at 50Ω terminal load connected to the RF connector

Table 4 RF Specifications

Parameter	Min	Typ	Max	Units
Frequency range	2400		2500	MHz
Receiver sensitivity		-103		dBm
Maximum input signal level	-20			dBm
Transmitter power at the maximum setting ²		20		dBm
Adjacent channel rejection		24		dB
Alternate channel rejection		42		dB
Carrier frequency error	-40		+40	ppm

² Ember RF output power programmed to -12 by emberSetRadioPower [2] or equivalent under NORMAL mode

5 Environmental Specifications

5.1 Absolute maximum ratings

Table 5 Absolute Maximum Rating

Symbol	Description	Min	Max	Units
T _{op}	Operating temperature	-40	85	°C
T _{st}	Storage temperature	-40	85	°C
V _{batt}	Power supply	-0.3	3.6	V
RFin	RF input power		10	dBm
MSL	Moisture Sensitivity Level	3		
RoHS	Restriction of Hazardous Substances	Compliant		

5.2 Operation conditions

Table 6 Recommended Operating Conditions

Symbol	Parameter	Min	Typ	Max	Units
V _{batt}	Power supply	2.4	3.0	3.4	V
T _{op}	Operating temperature	-40		85	°C

6 Application Information

6.1 Reference connection for UART host interface

Figure 5 illustrates the connections between SN3021 module and the host MCU via UART interface. A level shifter may be needed if the host UART interface level does not match with SN3021.

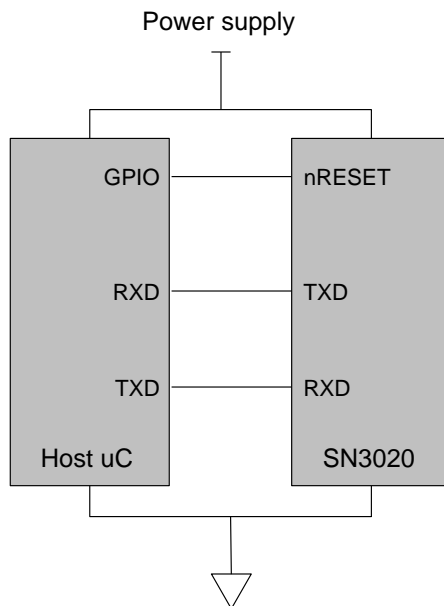


Figure 5 UART Host Interface Reference Diagram

6.2 Reference connection for the SPI host interface

Figure 6 illustrates the connections between SN3021 module and the host MCU via SPI interface.

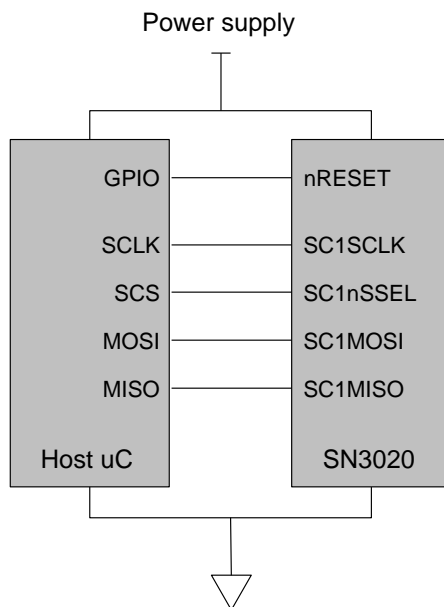


Figure 6 SPI Host Interface Reference Diagram

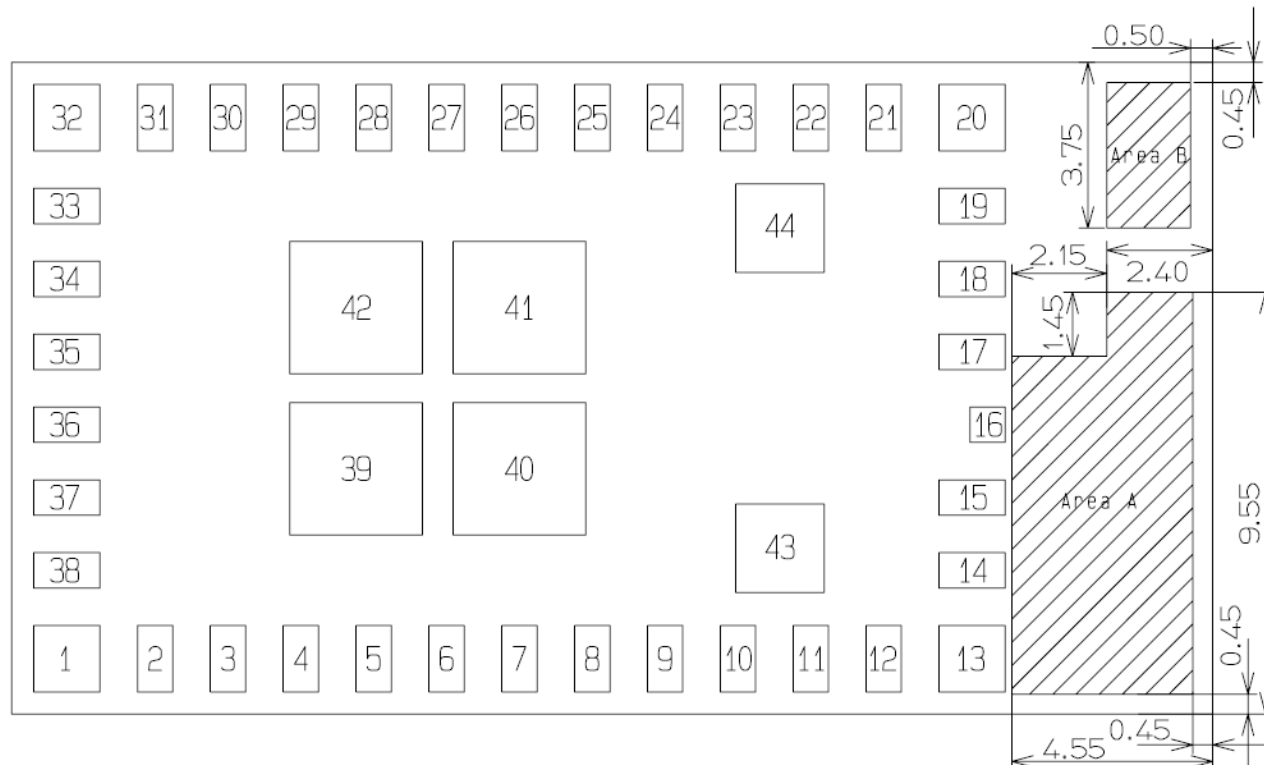


Figure 8 Recommended Host Circuit Board Design underneath the Module

Notes:

1. We recommend to use a filled via to pull RF signal out from RF pad (i.e. Pin 16).
2. If you don't use a filled via, RF trace from Pin 16 should go though "Area A" and "Area B" as little as possible.

7 Assembly Information

7.1 Lead-free soldering reflow profile

The lead-free solder reflow profile is recommended in the table & graph below. The profile is used to attach the module to its host PCB.

The module is designed to withstand 2 reflows. Opposite side reflow is prohibited due to the module weight.

Table 7 Reflow Profile Recommendation

Ramp up rate	3°C/second max
Maximum time maintained above 217°C	120 seconds
Peak temperature	250°C
Maximum time within 5°C of peak temperature	20 seconds
Ramp down rate	6°C/second max

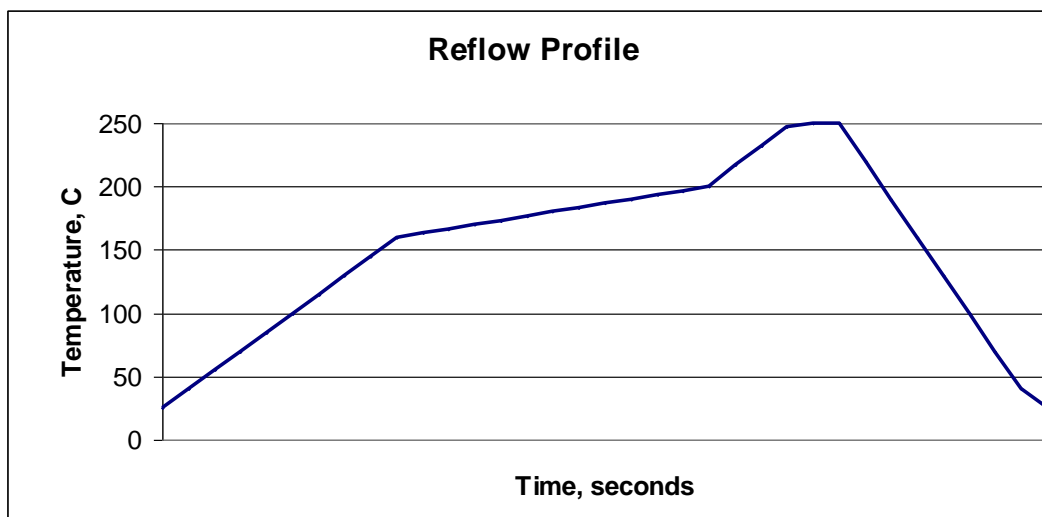


Figure 9 Reflow Profile Pattern

8 Package Information

8.1 Tape and reel specification

The product will be shipped in tape and reel package.

(1) Dimensions of tape (Plastic tape)

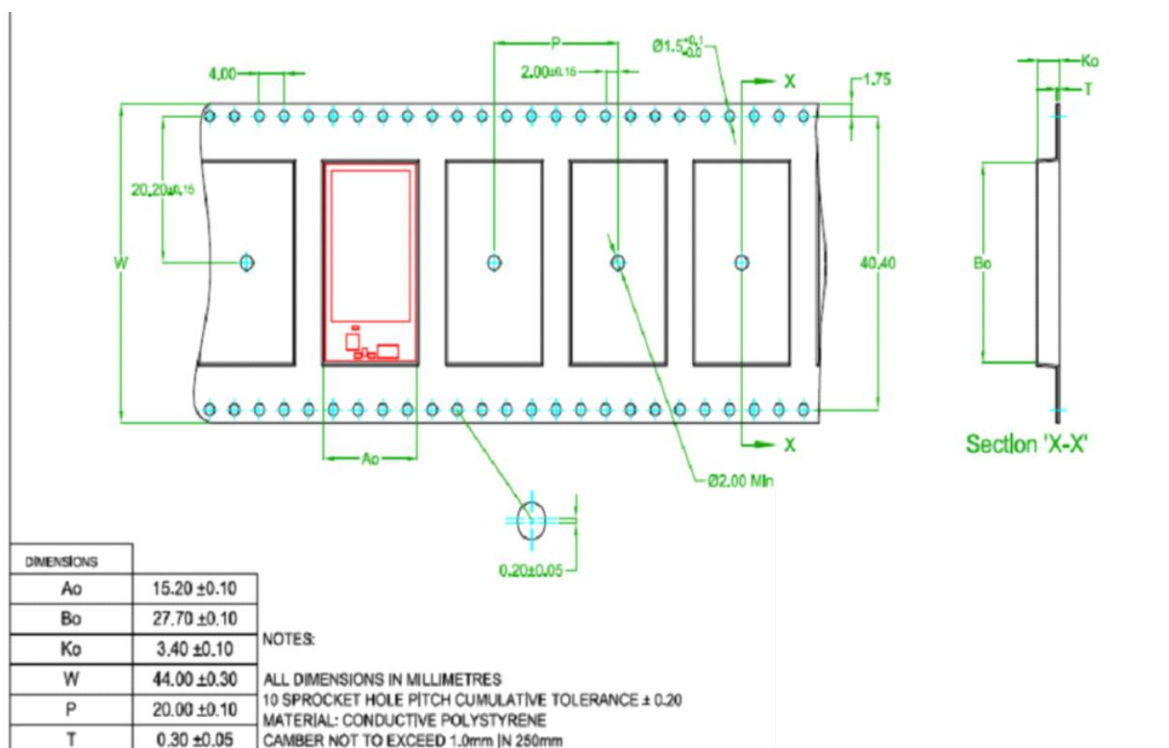


Figure 10 Tape Dimensions

8.2 Module Marking

The module will be marked using a label suitable for reflow soldering.

Table 8 Module Marking

Item	Description
A	Pin 1 ID
B	Model Name
C	MFG barcode in human readable form (includes module type, date code and serial number)

9 Ordering Information

Table 9 Ordering Information

Product	SyChip Model Number	SyChip Part Number
Evaluation kit	SN3021EVK	88-00144-85
Module	SN3021	88-00144-00

- -00 is for full production reel (950 pcs/reel)

10 RoHS Declaration

Given supplier declarations, this product does not contain substances that are banned by Directive 2002/95/EC or contains a maximum concentration of 0.1% by weight in homogeneous materials for

- Lead and lead compounds
- Mercury and mercury compounds
- Chromium (VI)
- PBB (polybrominated biphenyl)
- PBDE (polybrominated biphenyl ether)

And a maximum concentration of 0.01% by weight in homogeneous materials for

- Cadmium and cadmium compounds

11 Technical Support Contact

SyChip, LLC

2805 Dallas Parkway, Suite 400

Plano, TX 75093

USA

Tel: (972) 202-8900

Fax: (972) 633-0327

Note: SyChip, LLC is an operating unit within Murata Wireless Solutions

12 References

[1] IEEE Standard 802.15.4 – 2003 Wireless Medium Access Control (MAC) and Physical Layer (PHY) Specifications for Low-Rate Wireless Personal Area Networks (LR-WPANs)

[2] Ember, “EmberZNet API Reference: For the EM35x SoC Platform”, 120-3022-000G, October 28 2010

13 Disclaimer:

Please read this notice before using the SN3021 product.

1. Please note that the only warranty that SyChip LLC (“SyChip”) provides regarding the products is its conformance to the specifications provided herein. Accordingly, SyChip shall not be responsible for any defects in products or equipment incorporating such products, which are caused under the conditions other than those specified in this specification.

SYCHIP HEREBY DISCLAIMS ALL OTHER WARRANTIES REGARDING THE PRODUCTS, EXPRESS OR IMPLIED, INCLUDING WITHOUT LIMITATION ANY WARRANTY OF FITNESS FOR A PARTICULAR PURPOSE, THAT THEY ARE DEFECT-FREE, OR AGAINST INFRINGEMENT OF INTELLECTUAL PROPERTY RIGHTS. YOU AGREE TO INDEMNIFY AND DEFEND SYCHIP AND ITS AFFILIATES AGAINST ALL CLAIMS, DAMAGES, COSTS AND EXPENSES THAT MAY BE INCURRED, INCLUDING WITHOUT LIMITATION, ATTORNEY FEES AND COSTS, DUE TO THE USE OF PRODUCTS.

2. The product is designed and manufactured for general applications, and not for any particular application, so testing and use of the product shall be conducted at your own risk and responsibility. Specifically, please observe the following:

- i) Please conduct validation and verification of the products in actual condition of mounting and operating environment before commercial shipment of the equipment.
- ii) Please pay attention to minimize any mechanical vibration or shock, not to drop the product or a substrate that contains the product during transportation.
- iii) Since the application of static electricity or overvoltage may cause a defect in the product or deterioration of its reliability, caution must be taken against exposure to any static electricity generated by electrified items such as work benches, soldering irons, tools, carrying containers, etc.
- iv) Caution shall be taken to avoid overstress to the product during and after the soldering process.
- v) Since the applied soldering method may deteriorate the reliability, thorough evaluation is recommended.
- vi) In case the product is to be used in equipment or electric circuit that requires high safety or reliability function or performance, sufficient reliability evaluation checks for safety shall be performed before commercial shipment and moreover, due consideration to install a protective circuit is strongly recommended at customer's design stage. Please provide an appropriate fail-safe function on your product to prevent any damages that may be caused by the abnormal function or the failure of our product.

Notwithstanding the foregoing, the product shall not be used in any application listed below which requires especially high reliability for the prevention of such defect as may directly cause damage to the third party's life, body or property.

- Aircraft equipment
- Aerospace equipment
- Undersea equipment
- Power plant control equipment
- Medical equipment
- Transportation equipment (vehicles, trains, ships, etc.)
- Traffic signal equipment
- Disaster prevention / crime prevention equipment
- Application of similar complexity and/or reliability requirements to the applications listed in the above.

3. SyChip's warranty as provided in Clause 1 above that the products comply with descriptions expressly specified in the specifications shall be effective for a period of six (6) months from the date of delivery. SyChip shall not be liable for any defects that occur in dry packed products that are installed more than six (6) months after shipment.

SyChip's liability under this warranty shall be limited to products that are returned during the warranty period to the address designated by SyChip and that are determined by SyChip not to conform to such warranty. If SyChip elects to repair or replace such products, SyChip shall have reasonable time to repair such products or provide replacements. Repaired products shall be warranted for the remainder of the original warranty period. Replaced products shall be warranted for a new full warranty period.

For avoidance of doubt, SyChip shall not be liable for any defects that are caused by neglect, misuse or mistreatment by an entity other than SyChip including improper installation or testing, or for any products that have been altered or modified in any way by an entity other than SyChip. Moreover, SyChip shall not be liable for any defects that result from your or third party's design, specifications or instructions for such products.

4. Testing and other quality control techniques are used to the extent SyChip deems necessary. Unless mandated by government requirements, SyChip does not necessarily test all parameters of each product.

5. End of Life - Please note that we may discontinue the manufacture of products, due to reasons such as, but not limited to, end of supply of materials and/or components from our suppliers.

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